KetaSpire® CF10 HC AM Filament
polyetheretherketone

Ketaspire® CF10 HC AM Filament incorporates 10% carbon fiber reinforcement into a PEEK matrix for increased strength offered for use in high-performance healthcare applications. This material provides long-term performance up to 240 °C, including exceptional chemical resistance. These properties make it particularly suited for metal replacement.

General		
Material Status	• Commercial: Active	
Availability	• Africa & Middle East • Asia Pacific • Europe	• Latin America • North America
Filler / Reinforcement	• Carbon Fiber, 10% Filler by Weight	
Features	• Biocompatible • Chemical Resistant • Ductile • Flame Retardant	• Good Dimensional Stability • Good Impact Resistance • High Heat Resistance • High Strength
Uses	• Medical Devices	• Medical/Healthcare Applications
Agency Ratings	• ISO 10993	
RoHS Compliance	• Contact Manufacturer	
Appearance	• Black	
Forms	• Filament	
Processing Method	• 3D Printing, Fused Filament Fabrication (FFF)	

Physical	Typical Value	Unit	Test method
Density / Specific Gravity	1.33		ASTM D792
Diameter - Filament	1.8	mm	

Mechanical	Typical Value	Unit	Test method
Tensile Modulus	11000	MPa	ASTM D638
Tensile Strength (Break)	140	MPa	ASTM D638
Tensile Elongation (Break)	1.7	%	ASTM D638

Impact	Typical Value	Unit	Test method
Notched Izod Impact	89	J/m	ASTM D256

Thermal	Typical Value	Unit	Test method
Melting Temperature	343	°C	ASTM D3418

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Additional Information

Printing conditions for above data table:

- Filament drying conditions, minimum 4h: 150°C
- Extruder temperature: 400-440°C
- Bed temperature: 180-220°C
- Printing tool path: 0°

Test specimen parameters:

- First layer: 0.3mm thick
- Subsequent layers: 0.1mm
- 100% infill
- 3 shells
- Printing speed: 18 mm/s

Notes

Typical properties: these are not to be construed as specifications.

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Safety Data Sheets (SDS) are available by emailing us or contacting your sales representative. Always consult the appropriate SDS before using any of our products.

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